# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**  
[List multiple models if applicable.]

HP 210 G1 Notebook PC

---

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>screw driver, Philip #1 / TORX T</td>
</tr>
<tr>
<td>Description #2</td>
<td>screw driver, Philip #0 / TORX T</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove log low
2. remove battery pack
3. remove low cap l & r
4. remove DC-in
5. remove HDD & DDR & Wifi Module
6. remove lcd Module
7. remove log up
8. remove CRT & IO board
9. remove Speakers
10. remove log low
11. remove MB
12. remove Power & TP Board
13. remove TP Module
14. remove KB brk
15. remove KB
16. remove ESD Board
17. divide Display assy (remove LCD cover)
18. divide Display assy (remove LVDS Cable)
19. divide Display assy (remove Wifi)
20. divide Display assy (remove hinge)
21. divide Display assy (remove Wifi)
22. divide Display assy (remove Panel)
23. divide Display assy (remove touch screen)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1 Remove battery cells

Step 2 Remove Service door

Step 3 Remove low cap l & r

Step 4 Remove DC-in

Step 5 Remove HDD & DDR & Wifi Module

Step 6 Remove lcd Module
Step 7 Remove log up.

Step 8 Remove CRT & IO board

Step 9 Remove Speakers

Step 10 Remove log low

Step 11 Remove MB

Step 12 Remove Power & TP Board
Step 13 Remove TP Module

Step 14 Remove KB brk

Step 15 Remove KB Module

Step 16 Remove ESD board
Step 17: Remove LCD cover

Step 18: Remove LVDS cable

Step 19: Remove Wi-Fi

Step 20: Remove hinge
Step 21 Remove wifi

Step 22 Remove Panel

Step 23 Remove touch screen